Fan-out Wafer Level Packaging Cost Analysis

SavanSys cost modeling experts have put together a report on the current state of fan-out wafer level packaging costs. This report presents the most common process flows and evaluates each process segment. A detailed cost analysis is provided for each segment, utilizing sensitivity charts that highlight the cost impact of key variables such as material price, equipment price and throughput.

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Each Process Segment Analysis Includes:

Direct Cost per Wafer
Cost Structure
Cost Drivers
Sensitivity Analysis of Key Variables
Process Variations
..and more
See back of flier for examples!

Report delivered as a full written report
plus PowerPoint Slides

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Report release date: Q4 2016

SavanSys Solutions LLC has been in the cost modeling business for 20 years. SavanSys' activity based cost modeling approach is used throughout the supply chain by semiconductor giants, fabless companies, and equipment, material, and technology suppliers.

the SavanSys solution

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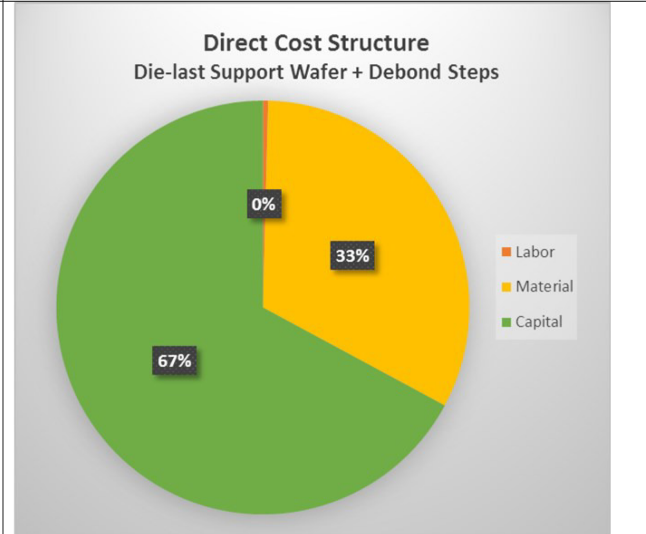
Example of Summary Level Process Segment Analysis

Cost Analysis Summary: Die-last Carrier Wafer and Debonding

Impact of this segment on total wafer cost:	Medium 8% of total cost (reference chart A)
Sensitive To:	Debond equipment and cost
Not Sensitive To:	Cost of reusable glass carrier
Per wafer cost:	10 to 25 dollars per wafer (reusable glass carrier)
Cost Structure:	

Examples of Sensitivity Charts and Activity Based Cost Output